Contact Name Title - Contact Product-Env-Stewards Product Enviro Compliance Authorized Representative* Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards Phone - Representative* Email - Representative* Email - Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company unique ID Unique ID Authority Response Date* 2024-10-06 Contact Name Title - Contact Title - Contact Product Enviro Compliance NA Product-Env-Stewards Outhorized Representative* Product-Env-Stewards Product-	752-21.1											als and Mf	g Informati	ion	
Semilar Sem	upplier Informa	ation													
Title - Contact Name Product Envis Compliance NA Na Intel Namia Compliance Na	Company name* Company unique ID				ique ID	ID Unique II		Jnique ID Auth	ique ID Authority			Response Date*			
Product-Env-Stewards	nsemi											2024-10-	06		
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Ite	Contact Name			Title - Contact			P	Phone - Contact*				Email - Contact*			
Product Envi-Stewards Requester Item Number Mfr Item Number Manufacturing Site Weight* UOM Unit LITEONFG 537.109 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			P	Phone - Representative*			Email - Representative*					
FOD4216SD 6PB RP SNUB T&R 2024-10-06 LITEONFG 537.109 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed CU Alloy Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds Comments	Requester	Requester Item Number Mfr Ite		m Number Mfr Item Name				Effective Date	Version Manufacturing Site		Anufacturing Site	V	Veight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Comments			FOD4216	5SD	6PB RP SNUB T&	R		2024-10-06		L	ITEONFG	5	37.109	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Paga	Alloy	STD 020 MSL	Pating	Dook Prog	ass Pady To	mporatur	May Time at Peak	Tamparatu	ro Numb	per of Poflow Cyc	Jac
omments					Alloy J-S	31D-020 WSL	Katilig		ess Body Te					bei of Kellow Cyc	ies
	•	i (Sii) • aimeaieu	C	O Alloy	1			400		<u> </u>	30	second	15 3		
ver 1 - maximum time at peak temperature during soldering is 10-30 seconds		me at neals temperature	during cal	doring is 10.3	0 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose al applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	1.83	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.635	mg
			Supplier	Dimethyl Siloxane	68083-19-2		0.888	mg
			Supplier	3-Methacryloxypropyltrimethoxysilane (C10H20O5Si)	2530-85-0		0.307	mg
Die	4.043	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.283	mg
			Supplier	Silicon (Si)	7440-21-3		3.76	mg
Die Attach	1.665	mg	Supplier	Silver (Ag)	7440-22-4		1.2487	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.4162	mg
Lead Frame	108.322	mg	Supplier	Silver (Ag)	7440-22-4		0.68	mg
			Supplier	Zinc (Zn)	7440-66-6		0.13	mg
			Supplier	Iron (Fe)	7439-89-6		2.48	mg
			Supplier	Copper (Cu)	7440-50-8		105	mg
			Supplier	Phosphorus (P)	7723-14-0		0.032	mg
Mold Compound-Black	414.4	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		16.6	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		95.3998	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		12.4	mg
			Supplier	Carbon Black (C)	1333-86-4		4.15	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		285.8498	mg
Plating	6.7	mg	Supplier	Tin (Sn)	7440-31-5		6.7	mg
Wire Bond - Au	0.149	mg	Supplier	Gold (Au)	7440-57-5		0.149	mg